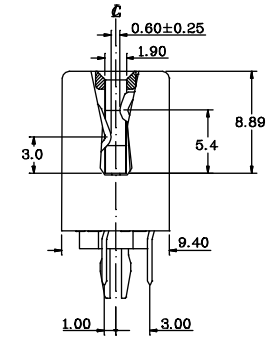


Section X-X



Section Y-Y

**ELECTRICAL:**

CURRENT: 1A  
 CAPACITANCE: < 2 PF  
 CONTACT RESISTANCE: < 15mΩ  
 INSULATOR RESISTANCE: > 1000MΩ  
 DIELECTRIC WITHSTANDING VOLTAGE: 500VAC FOR 1 MIN.

**MATERIAL:**

BODY: High Temperature Thermoplastic (UL94V-0)  
 CONTACTS: Copper Alloy  
 RETENTION CLIP: Copper Alloy  
 CONTACT PLATING: Gold Plating Over Nickel on Contact Area  
 Tin/Lead Plating on Terminal

**HOW TO ORDER:**

B 0 4 2 - 1 8 0 0 - 0 0 0 - Z

**NUMBER OF CONTACTS:**

180

**RoHS COMPLIANT**

Rev	Drawn	Checked	Approved	Date
0 Issued	A.M.	S.M.	S.M.	04/03/03
A Revised for RoHS Compliance	B.S.	S.M.	S.M.	12/15/06

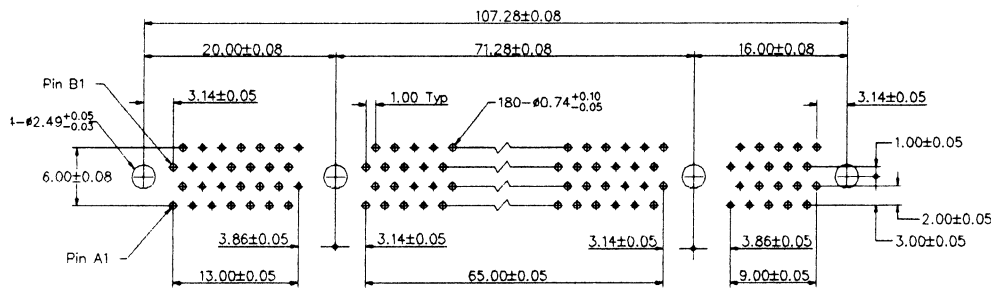
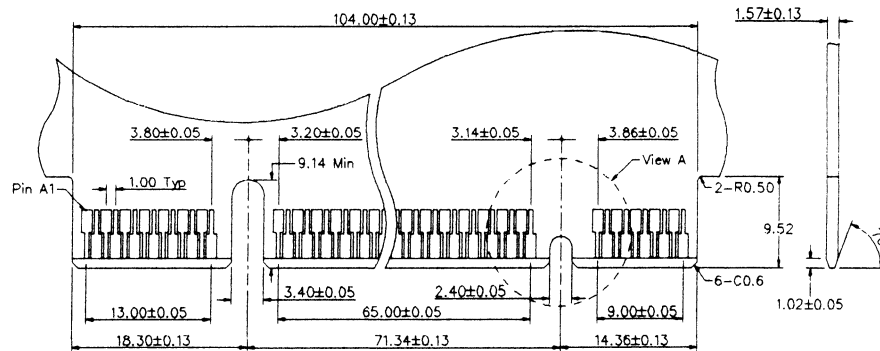
**SMP TECHNOLOGY, INC.**

SCALE	MAT'L	FINISH
TOL. DEC.	.X +/- 0.38	.XX +/- 0.25
	.XXX +/- 0.20	ANGLE +/- 3°
		UNIT: mm

AGP PRO - 180 Position (1.5 Volt)

P/N: B042-1800-000-Z

180 Daughter Card Requirements



**ELECTRICAL:**

CURRENT: 1A  
 CAPACITANCE: < 2 PF  
 CONTACT RESISTANCE: < 15mΩ  
 INSULATOR RESISTANCE: > 1000MΩ  
 DIELECTRIC WITHSTANDING VOLTAGE: 500VAC FOR 1 MIN.

**HOW TO ORDER:**

**B 0 4 2 - 1 8 0 0 - 0 0 0 - Z**

**NUMBER OF CONTACTS:**

180

**RoHS COMPLIANT**

**MATERIAL:**

BODY: High Temperature Thermoplastic (UL94V-0)  
 CONTACTS: Copper Alloy  
 RETENTION CLIP: Copper Alloy  
 CONTACT PLATING: Gold Plating Over Nickel on Contact Area  
 Tin/Lead Plating on Terminal

Rev	Drawn	Checked	Approved	Date	<b>SMP TECHNOLOGY, INC.</b>
0 Issued	A.M.	S.M.	S.M.	04/03/03	
A Revised for RoHS Compliance	B.S.	S.M.	S.M.	12/15/06	
SCALE                      MAT'L                      FINISH                      AGP PRO - 180 Position (1.5 Volt)					
TOL. DEC.	.X +/- 0.38	.XX +/- 0.25	.XXX +/- 0.20	ANGLE +/- 3°      UNIT: mm	P/N: B042-1800-000-z